

**MOLEX MATERIAL SPECIFICATION – C51900 ALLOY METAL STRIPS**

**1. SCOPE**

This specification covers the comprehensive technical requirements, applicable reference documents, and quality requirements for metal strips. The values listed for acceptance criteria are in SI units.

**2. PURPOSE**

The purpose of this specification is 1) to comprehensively define the Molex requirements for the alloy's chemical composition, physical properties, mechanical properties, and 2) to reference other applicable documents related to quality requirements and dimensional tolerances.

This specification meets or exceeds the requirements cited in the primary regional norms typically referenced for copper alloy strip manufacture in UNS C51900 alloy; ASTM B103M, EN 1654 (CuSn6), and JIS H 3110 (C5191).

**3. REFERENCE DOCUMENTS**

This primary specification focuses on the physics of C51900 alloy and related mechanical properties to assure Molex product performance. These reference documents are crucial to the Molex process / product and therefore all requirements contained within them must be attested to and demonstrate their conformance, within the supplier's process certification:

- ASTM B103M and the associated reference documents listed under *2.1 ASTM Standards*
- ASTM B820 is specifically mentioned as critical to Molex formability requirements
- JIS H3110 and UFG supplier citations (< 4µm)
- 2090580043 Geometric Conditions and Tolerances for Metal Strips
- 2090580044 Metal Strip Surface conditions and Requirements

**4. ORDER OF PRECEDENCE**

This defines the priority order that should be followed when reviewing attributes and requirements of metal strip:

1. Molex Purchase Order
2. Packaging Specifications
3. Molex (Individual) Metal Strip Specification (i.e. Part Number Specification)
4. Molex Material Alloy Specification (**This document – 22090580062 – Molex Material Specification – C51900 Alloy Metal Strips**)
5. Surface (2090580044) and Geometric (2090580043) Global Engineering Specifications

THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISION DESCRIPTION	NEW RELEASE			<b>MOLEX MATERIAL SPECIFICATION– C51900 ALLOY METAL STRIPS</b>			
CHANGE NO.	849683						
REVISED BY	DATE			DOC TYPE	DOC TYPE DESCRIPTION	DOC PART	SERIES
REV APPR BY	DATE			QMD	ENGINEERING STANDARD	000	209058
INITIAL RELEASE				CUSTOMER	DOCUMENT NUMBER	REVISION	SHEET
INITIAL DRWN	RYAN YINKSAMIEC	DATE	2026/04/15	MOLEX INTERNAL	<b>2090580062</b>	<b>A</b>	1 OF 5
INITIAL APPR	DANIEL MOLLA	DATE	2026/04/15				

**5. DEFINITIONS**

Ultrafine grain (UFG) – is defined as a “ready-to-finish” grain size of less than 0.004 mm (< 4µm).

**6. TECHNICAL REQUIREMENTS**

**6.1 Chemical Composition**

UNS #	Cu wt.%	Pb wt.%	Fe wt.%	P wt.%	Sn wt.%	Zn wt.%
C51900 <sup>1</sup>	Remainder <sup>2</sup>	≤ 0.05	≤ 0.10	0.03 – 0.35	5.0 – 7.0	≤ 0.30

- Limits for unnamed elements may be established between Molex and the supplier to satisfy certain environmental or customer requirements.
- Copper + Sum of Named Elements = 99.5% min.

**6.2 Mechanical Properties (longitudinal direction)**

Mechanical Properties Table C51900				
Designation	Tensile Strength (1) (MPa)	Yield Strength (1) 0.2% offset (MPa)	Elongation % in 50 mm	RTF Grain size (2) (mm)
O61	≥ 315	N/A as per H3110	≥ 42	N/A
H01	390 - 510	≥ 360	≥ 35	≤ 0.030
H02	490 - 610	≥ 420	≥ 20	≤ 0.010
H03	500 – 590	≥ 460	≥ 8	≤ 0.010
H04	590 - 685	≥ 510	≥ 8	≤ 0.010
H04 UFG	550 - 650	≥ 500	≥ 16	< 0.004
H06	635 - 725	≥ 570	≥ 5	≤ 0.010
H06 UFG	635 – 725	≥ 570	≥ 8	< 0.004
H08	≥ 690	≥ 620	≥ 1	≤ 0.010
H08 UFG	670 - 780	≥ 660	≥ 7	< 0.004

Notes:

- Tensile requirements are longitudinal values in uniaxial tension in accordance with ASTM E8M.
- Ready to Finish (RTF) grain size is measured before final rolling for the H tempers.

**6.3 Electrical Conductivity** (SnP bronze conductivity is strongly influenced by chemical composition).

6.3.1 The test standard shall be ASTM E 1004 (eddy current) or ASTM B 193 (resistivity).

THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISION DESCRIPTION	NEW RELEASE			<b>MOLEX MATERIAL SPECIFICATION– C51900 ALLOY METAL STRIPS</b>			
CHANGE NO.	849683						
REVISED BY	DATE	DOC TYPE	DOC TYPE DESCRIPTION	DOC PART	SERIES		
REV APPR BY	DATE	QMD	ENGINEERING STANDARD	000	209058		
INITIAL RELEASE		CUSTOMER	DOCUMENT NUMBER	REVISION	SHEET		
INITIAL DRWN	RYAN YINKSAMIEC	DATE	2026/04/15	MOLEX INTERNAL	2090580062	A	2 OF 5
INITIAL APPR	DANIEL MOLLA	DATE	2026/04/15				

	Conductivity @ 20°C (%IACS)
O61	13% - 18%
H01	13% - 18%
H02	13% - 18%
H04	13% - 18%
H04 UFG	13% - 18%
H06	13% - 17%
H06 UFG	13% - 17%
H08	13% - 17%
H08 UFG	13% - 17%

Note: The acceptance is determined by the minimum value.

**6.4 Bending properties**

Bending of metal strip samples shall be in accordance with ASTM B820; Bend Test for Formability of Copper Alloy Spring Material. The requirement is that the supplier’s material when tested at finished thickness and temper, will be capable of achieving the inside bend radii as listed in the tables below without observable cracking on the outside bend radius (reference 5.4.1.) At a minimum, samples shall be tested in both directions, at 180° of bending, at the most representative thickness category for the metal strip purchase order.

If special forming requirements are necessary, those will be listed separately on the part number document.

<b>H04</b>	Thickness	90° GW	180° GW	90° BW	180° BW	<b>H04 UFG</b>	Thickness	90° GW	180° GW	90° BW	180° BW
	0.51-1.0 mm	10:1 w/t		10:1 w/t			Thickness	10:1 w/t		10:1 w/t	
	0.3-0.5 mm	-	-	-	-		0.51-1.0 mm	-	-	-	-
	0.15-0.29 mm	0.5 r/t	2.0 r/t	1.0 r/t	3.0 r/t		0.3-0.5 mm	0.25 r/t	0.5 r/t	0.25 r/t	1.0 r/t
	≤0.149 mm	0.5 r/t	2.0 r/t	1.0 r/t	3.0 r/t		0.15-0.29 mm	0.25 r/t	0.5 r/t	0.25 r/t	1.0 r/t
<b>H06</b>	Thickness	90° GW	180° GW	90° BW	180° BW	<b>H06 UFG</b>	Thickness	90° GW	180° GW	90° BW	180° BW
	0.51-1.0 mm	10:1 w/t		10:1 w/t			Thickness	10:1 w/t		10:1 w/t	
	0.3-0.5 mm	-	-	-	-		0.51-1.0 mm	-	-	-	-
	0.15-0.29 mm	1.0 r/t	3.0 r/t	3.5 r/t	4.0 r/t		0.3-0.5 mm	0.5 r/t	1.0 r/t	1.0 r/t	2.0 r/t
	≤0.149 mm	1.0 r/t	3.0 r/t	3.5 r/t	4.0 r/t		0.15-0.29 mm	0.5 r/t	1.0 r/t	1.0 r/t	2.0 r/t
<b>H08</b>	Thickness	90° GW	180° GW	90° BW	180° BW	<b>H08 UFG</b>	Thickness	90° GW	180° GW	90° BW	180° BW
	0.51-1.0 mm	10:1 w/t		10:1 w/t			Thickness	10:1 w/t		10:1 w/t	
	0.3-0.5 mm	-	-	-	-		0.51-1.0 mm	-	-	-	-
	0.15-0.29 mm	2.0 r/t	4.0 r/t	7.0 r/t	12.0 r/t		0.3-0.5 mm	1.0 r/t	2.0 r/t	2.0 r/t	3.5 r/t
	≤0.149 mm	2.0 r/t	4.0 r/t	7.0 r/t	12.0 r/t		0.15-0.29 mm	1.0 r/t	2.0 r/t	2.0 r/t	3.5 r/t






THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISION DESCRIPTION	NEW RELEASE			<b>MOLEX MATERIAL SPECIFICATION- C51900 ALLOY METAL STRIPS</b>			
CHANGE NO.	849683						
REVISED BY	DATE		DOC TYPE	DOC TYPE DESCRIPTION	DOC PART	SERIES	
REV APPR BY	DATE		QMD	ENGINEERING STANDARD	000	209058	
INITIAL RELEASE			CUSTOMER	DOCUMENT NUMBER	REVISION	SHEET	
INITIAL DRWN	RYAN YINKSAMIEC	DATE	2026/04/15	MOLEX INTERNAL	2090580062	A	3 OF 5
INITIAL APPR	DANIEL MOLLA	DATE	2026/04/15				

Notes:

- (1) W/t = width to thickness ratio (defining bending width). r/t = inside bend radius to thickness ratio
- (2) It is the expectation that tempers lower than H04 will possess bend formability that is as good (or better) than the values listed for the H04 temper.

**6.4.1 Acceptance Criteria for Bending**

Bending Observations	Acceptance Criteria	Rank
	"Accepted", smooth, no orange peel, no cracks	1
	"Accepted", small orange peel, no cracks	2
	"Accepted", heavy orange peel, no cracks	3
	"Rejected", heavy orange peel, shallow cracks	4
	"Rejected", heavy orange peel, deep cracks	5

**6.5 Thermal Stress Relaxation Resistance (Nominal expected performance as measured by the Ring Method in compliance with ASTM E328)**

C51900 Alloy Thermal Stress Relaxation - Percent Retained @ 1000 Hours						
Temp °C	50% Rp <sub>0.2</sub>	80% Rp <sub>0.2</sub>	100% Rp <sub>0.2</sub>	50% Rp <sub>0.2</sub> ⊥	80% Rp <sub>0.2</sub> ⊥	100% Rp <sub>0.2</sub> ⊥
75	99%	99%	99%	99%	99%	99%
100	93%	93%	93%	93%	93%	93%
125	82%	82%	82%	82%	82%	82%
150	66%	66%	66%	66%	66%	66%

Note:

- 1. Rp<sub>0.2</sub> is equivalent to 0.2% offset Yield strength
- 2. This table represents the "Thermal Stress Relaxation" in the precipitation hardened state, common in most Molex applications. The values shown are intrinsic material characteristics primarily governed by alloy composition and are therefore independent of the applied stress level. What is not represented here is certain types of supplier processing such as, final cold rolling, stretch-bend-levelling, etc., that negatively influence the stress relaxation curve. Additional strong negative influences come from the types and intensities of part forming processes along with the strain component applied at the separable interface. Therefore, this thermal relaxation is only one component of the total relaxation that could be experienced in use.

THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISION DESCRIPTION	NEW RELEASE			<b>MOLEX MATERIAL SPECIFICATION- C51900 ALLOY METAL STRIPS</b>			
CHANGE NO.	849683						
REVISED BY	DATE			DOC TYPE	DOC TYPE DESCRIPTION	DOC PART	SERIES
REV APPR BY	DATE			QMD	ENGINEERING STANDARD	000	209058
INITIAL RELEASE				CUSTOMER	DOCUMENT NUMBER	REVISION	SHEET
INITIAL DRWN	RYAN YINKSAMIEC	DATE	2026/04/15	MOLEX INTERNAL	<b>2090580062</b>	<b>A</b>	4 OF 5
INITIAL APPR	DANIEL MOLLA	DATE	2026/04/15				

**7. CERTIFICATION REQUIREMENTS**

Certification at P.O. Level	Supplied Data at P.O. Level	Annual Capability Statement	Engineering Data by Request
Chemical Composition (data)		Chemical Capability	
Tensile (data)		Tensile Capability	Transverse properties
Yield (data)		Yield Capability	Spring Bending Limit
Elongation (data)			
Grain size (data)			
			Elastic Modulus (data)
Thickness (data)		Thickness Capability	
Width (data)		Width Capability	
Camber (pass/fail)			
Surface Roughness (data)			
		Stress Relaxation Verification	
Burr (pass/fail)			
Bend Formability (pass/fail)			ASTM B820 Appendix narrow beam reporting table, or other
Electrical Conductivity (data)			
			Other Physical Properties
Reference Documents (pass/fail)			

**6.1 Requirements for “Annual Capability Assessment” of critical characteristics**

- 6.1.1 Chemical composition requires a statistical assessment on an annual basis to verify capability. This assessment be on file and available to Molex when requested.
- 6.1.2 Mechanical properties, requires a statistical assessment on an annual basis to verify capability. This assessment be on file and available to Molex when requested.
- 6.1.3 Dimensional tolerances, requires a statistical assessment on an annual basis to verify capability. This assessment be on file and available to Molex when requested.
- 6.1.4 Stress relaxation resistance is to be verified for a temper and a process in the H04 to H08 designation range at 100% of yield strength for 1000 hours at 75°C and 125°C. The supplier shall select an active Molex item to fulfill this requirement. It is acceptable to utilize Larson Miller Parameters to facilitate this annual verification audit.

**6.2 Engineering Data**

Acceptance of this material specification and the requirements include the supplier’s commitment to provide other engineering data when requested. These types of data may include transverse properties, spring bending limits or other physical properties of this material.

**6.3 Recent Change Summary**

Initial Release.

THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISION DESCRIPTION	NEW RELEASE			<b>MOLEX MATERIAL SPECIFICATION– C51900 ALLOY METAL STRIPS</b>			
CHANGE NO.	849683						
REVISED BY		DATE		DOC TYPE	DOC TYPE DESCRIPTION	DOC PART	SERIES
REV APPR BY		DATE		QMD	ENGINEERING STANDARD	000	209058
INITIAL RELEASE				CUSTOMER	DOCUMENT NUMBER	REVISION	SHEET
INITIAL DRWN	RYAN YINKSAMIEC	DATE	2026/04/15	MOLEX INTERNAL	<b>2090580062</b>	<b>A</b>	5 OF 5
INITIAL APPR	DANIEL MOLLA	DATE	2026/04/15				